Dynamic Contamination Control Of Equipment Controlled By A Split Runcard

ABSTRACT OF THE DISCLOSURE

A method for dynamically maintaining compatible contamination levels of equipment, wafer Lots and FOUP's used for automated processing of a Split Lot of wafers. Processing of the test Lot and the production Lot continue as a single Lot along the production processing path up to a split condition process. Processing of the production Lot is put on hold and its designated contamination level is saved until the alternate processing or test Lot processing is completed. The contamination level of the Split Lot is reevaluated based on the completed process(es) and will be designated at the same level it carried at the Split or a higher contamination level if appropriate. The two Lots are then merged and given the highest contamination level of either the saved level or the Split Lot. The two Lots are then processed according to the original predefined process steps and at the redefined contamination level.

FIG. 2